

# INSTRUCTIONS FOR USE



## CWB/18-60-MVS

Tool to remove bonded semiconductor with chamfer on the semiconductor cutback and stop for MV cable

### RECOMMENDATIONS :

Using instructions should be read before any use of tool.

### FUNCTION AND CABLE :

Silicon free tool aimed to remove the semi conductive layer with a transition chamfer. Its comes with a MVS stop aimed to have a perfect and straight semiconductor cutting end.

Cable range from Ø18 to Ø60mm / Ø0,709 to Ø2,362in on the semi conductive layer.

### SECTION :

MV Semiconductor

### APPLICATIONS :

Field, Laboratory

### ADAPTED PERSONAL PROTECTIVE EQUIPMENT :

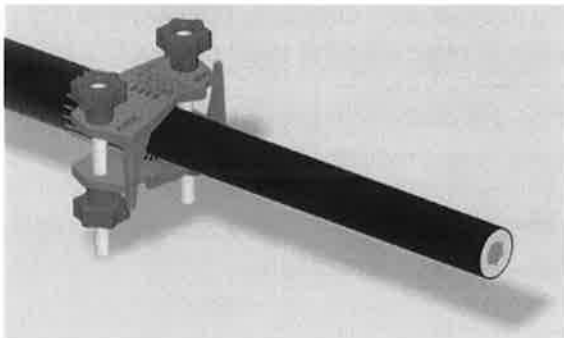
Cut-resistant gloves, glasses, safety shoes.

The tool should be used only for its functions on appropriate cables.

Do not use when the cable is under tension.

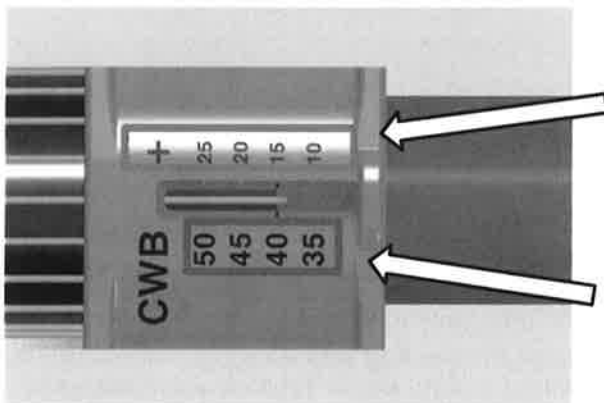
## INSTRUCTIONS :

### 1 – Positioning of the MVS stop



- Put the MVS stop on the cable outer sheath, the two brackets of the stop oriented towards the cable end.
- Tighten progressively on both sides the tightening buttons to lock the stop

### 2 – Adjustment of remaining length of bonded semi-conductive layer



- With another tool, please use **column +**.
- For example: Aligning with the 15-value, you will obtain 15 mm of remaining **length besides the thickness of tool used**.
- With the CWB tool, use the CWB column.
- Align the value of remaining length with the cable end.
- For example with the 40-value, you will obtain 40 mm of remaining length. (CWB width is taken into account on the graduation)

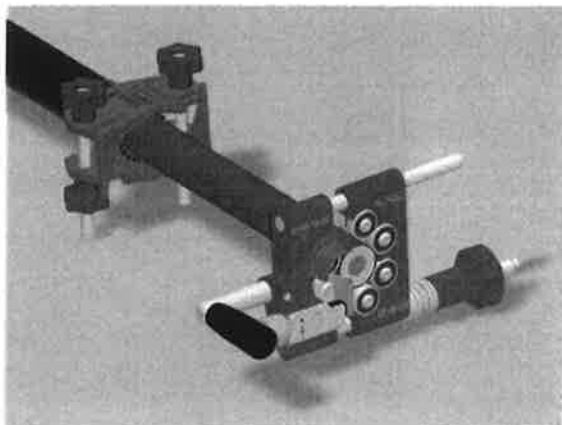
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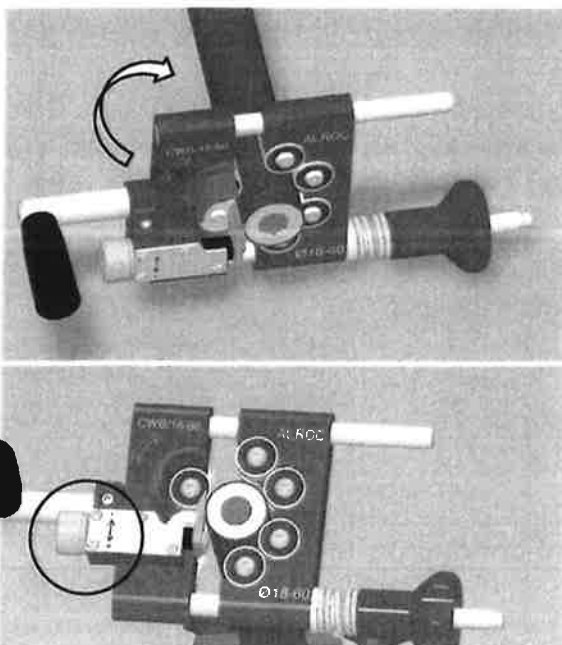
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### 3 – Positioning of the CWB tool



- Make sure, than the blade is in the up position.
- Position the CWB tool at the cable end and tighten it by turning the red button.

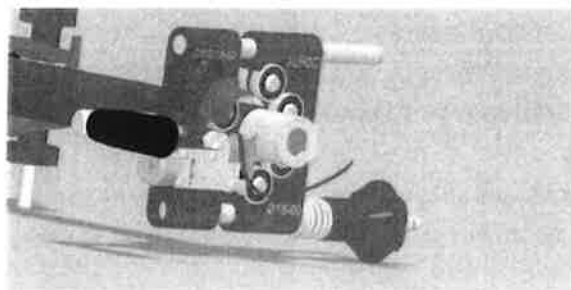
### 4 – Adjustment of cutting depth



- Keeping the blade up, move the tool forward by rotating it, clockwise direction, until to have the entire blade overhead the semi conductive layer.
- Advance the blade with brass button in order to touch the semiconductor.
- Bring back the tool at the cable end by turning it in counter-clockwise direction.
- Adjust the blade depth by rotating the golden button :

**1 clic = 0,1 mm / 0,004 in**

### 5 – Pelling the semiconductor



- Peel on 3 to 4cm / 1,181 to 1,575in and adjust the depth if necessary.
- Pass the chip around the handle and make a knot around the cable to lock it.
- Continue the peeling with a regular rotation of the tool without using force. Tool moves forward by itself while turning.

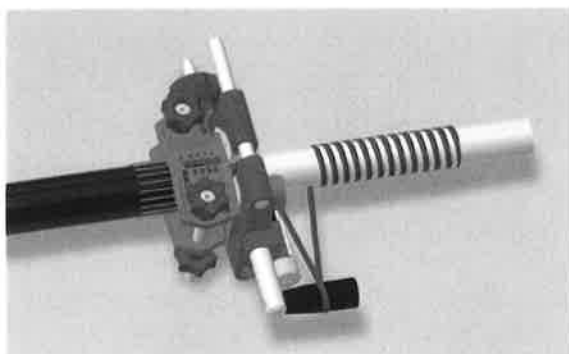
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### 6 – Stop of the tool



- Keep peeling until to get in contact with MVS stop.
- After contact, make one or two turns more to break the chip.
- Back up the blade, untighten the tool and remove it from the cable.
- Untighten and remove the stop from the cable.

## SPARE PARTS :



- Spare blade for CWB/18-60-MVS  
Chamfer angle : 13°

**REFERENCE : LCWB-FEP**



- Alternative stop for a clean and straight cutting end

**REFERENCE : MVS**

### Guarantee :

The tool is guaranteed during one year from the date of reception, apart from organs of cut and wearing parts.

This guarantee includes all the defects result in materials, components, fabrication or mounting.

All defect resulting from non-compliant use will not be taken into the guarantee.

All maintenance operations other than the change of blade will must be done by the fabricant or by approved ALROC.

### Recycling :

The tool must not be throw in domestic waste. The tool must be return at the fabricant or recycled according to materials who compose it.